

ABSTRACT

ILLUMINATION APPARATUS FOR IRRADIATING DICING TAPE AND METHOD OF ILLUMINATION THEREOF

An illumination apparatus for irradiating a workpiece in order to weaken the adhesive strength of a photo-setting adhesive used to bond a semiconductor wafer to dicing tape includes a chamber for holding the workpiece, a high pressure mercury lamp for irradiating the workpiece, a power source equipped with an inverter to supply a rectangular waveform alternating current to the lamp, a reflecting mirror for reflecting light emitted by the lamp, guide rails which enable the chamber to be moved, an operation portion for setting the speed of motion of the chamber along the guide rails, a light detecting sensor to detect the illumination intensity of the light emitted by the lamp, a base illumination intensity setting portion for setting a base illumination intensity, a control portion equipped with a microcomputer for controlling the power outputted from the power source to the lamp to cause the lamp to emit light at the set base illumination intensity, and a drive portion to move the chamber at the speed set by the operation portion.

This Sheet Has Been Replaced



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